

Fast Thyristor Type FDT32-400-24

Low switching losses / Low reverse recovery charge

Distributed amplified gate for high di_T/dt

Mean on-state current	I_{TAV}	400 A	
Repetitive peak off-state voltage	V_{DRM}		
Repetitive peak reverse voltage	V_{RRM}	2000...2400 V	
Turn-off time	t_q	50.0, 63.0 μs	
V_{DRM}, V_{RRM}, V	2000	2200	2400
Voltage code	20	22	24
$T_j, ^\circ C$		-60...+125	

MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Mean on-state current	A	371 400 544	$T_c= 85^\circ C$; Double side cooled; $T_c= 80^\circ C$; Double side cooled; $T_c= 55^\circ C$; Double side cooled; 180° half-sine wave; 50 Hz	
I_{TRMS}	RMS on-state current	A	628	$T_c= 80^\circ C$; Double side cooled; 180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	6.6 7.5	$T_j=T_{j \max}$ $T_j=25^\circ C$	180° half-sine wave; $t_p=10$ ms; single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=50$ μs ; $di_G/dt=1$ A/ μs
			7.0 8.0	$T_j=T_{j \max}$ $T_j=25^\circ C$	180° half-sine wave; $t_p=8.3$ ms; single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=50$ μs ; $di_G/dt=1$ A/ μs
I^2t	Safety factor	$A^2 \cdot 10^3$	210 280	$T_j=T_{j \max}$ $T_j=25^\circ C$	180° half-sine wave; $t_p=10$ ms; single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=50$ μs ; $di_G/dt=1$ A/ μs
			200 260	$T_j=T_{j \max}$ $T_j=25^\circ C$	180° half-sine wave; $t_p=8.3$ ms; single pulse; $V_D=V_R=0$ V; Gate pulse: $I_G=I_{FGM}$; $V_G=20$ V; $t_{GP}=50$ μs ; $di_G/dt=1$ A/ μs
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	2000...2400	$T_{j \min} < T_j < T_{j \max}$; 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	2100...2500	$T_{j \min} < T_j < T_{j \max}$; 180° half-sine wave; single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.6 \cdot V_{DRM}$ $0.6 \cdot V_{RRM}$	$T_j=T_{j \max}$; Gate open	

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TRIGGERING				
I_{FGM}	Peak forward gate current	A	6	$T_j = T_{j\max}$
V_{RGM}	Peak reverse gate voltage	V	5	
P_G	Gate power dissipation	W	3	$T_j = T_{j\max}$ for DC gate current
SWITCHING				
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	A/ μ s	1600	$T_j = T_{j\max}$; $V_D = 0.67 \cdot V_{DRM}$; $I_{TM} = 1700$ A; Gate pulse: $I_G = 2$ A; $V_G = 20$ V; $t_{GP} = 50 \mu$ s; $di_G/dt = 2$ A/ μ s
THERMAL				
T_{stg}	Storage temperature	°C	-60...+50	
T_j	Operating junction temperature	°C	-60...+125	
MECHANICAL				
F	Mounting force	kN	9.0...11.0	
a	Acceleration	m/s ²	50	Device clamped

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions		
ON-STATE						
V_{TM}	Peak on-state voltage, max	V	2.20	$T_j = 25$ °C; $I_{TM} = 1256$ A		
$V_{T(TO)}$	On-state threshold voltage, max	V	1.248	$T_j = T_{j\max}$;		
r_T	On-state slope resistance, max	$m\Omega$	0.992	$0.5 \pi I_{TAV} < I_T < 1.5 \pi I_{TAV}$		
I_H	Holding current, max	mA	500	$T_j = 25$ °C; $V_D = 12$ V; Gate open		
BLOCKING						
I_{DRM}, I_{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	50	$T_j = T_{j\max}$; $V_D = V_{DRM}$; $V_R = V_{RRM}$		
$(dv_D/dt)_{crit}$	Critical rate of rise of off-state voltage ¹⁾ , min	V/ μ s	200, 320, 500, 1000, 1600, 2000, 2500	$T_j = T_{j\max}$; $V_D = 0.67 \cdot V_{DRM}$; Gate open		
TRIGGERING						
V_{GT}	Gate trigger direct voltage, max	V	3.00 2.50 1.50	$T_j = T_{j\min}$ $T_j = 25$ °C $T_j = T_{j\max}$	$V_D = 12$ V; $I_D = 3$ A; Direct gate current	
I_{GT}	Gate trigger direct current, max	mA	500 300 150	$T_j = T_{j\min}$ $T_j = 25$ °C $T_j = T_{j\max}$		
V_{GD}	Gate non-trigger direct voltage, min	V	0.35	$T_j = T_{j\max}$; $V_D = 0.67 \cdot V_{DRM}$;		
I_{GD}	Gate non-trigger direct current, min	mA	35.00	Direct gate current		
SWITCHING						
t_{gd}	Delay time, max	μ s	0.85	$T_j = 25$ °C; $V_D = 1000$ V; $I_{TM} = I_{TAV}$; $di/dt = 200$ A/ μ s;		
t_{gt}	Turn-on time ²⁾ , max	μ s	2.00, 2.50, 3.20, 4.00	Gate pulse: $I_G = 2$ A; $V_G = 20$ V; $t_{GP} = 50 \mu$ s; $di_G/dt = 2$ A/ μ s		
t_q	Turn-off time ³⁾ , max	μ s	50.0, 63.0	$dv_D/dt = 50$ V/ μ s	$T_j = T_{j\max}$; $I_{TM} = I_{TAV}$; $di_R/dt = -10$ A/ μ s; $V_R = 100$ V; $V_D = 0.67 \cdot V_{DRM}$	
			63.0, 80.0	$dv_D/dt = 200$ V/ μ s		
Q_{rr}	Total recovered charge, max	μ C	400	$T_j = T_{j\max}$; $I_{TM} = 400$ A;		
t_{rr}	Reverse recovery time, typ	μ s	5.0	$di_R/dt = -50$ A/ μ s;		
I_{rrM}	Peak reverse recovery current, max	A	160	$V_R = 100$ V		

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THERMAL					
R_{thjc}	Thermal resistance, junction to case, max	$^{\circ}\text{C}/\text{W}$	0.0500	Direct current	Double side cooled
R_{thjc-A}			0.1100		Anode side cooled
R_{thjc-K}			0.0900		Cathode side cooled
R_{thck}	Thermal resistance, case to heatsink, max	$^{\circ}\text{C}/\text{W}$	0.0060	Direct current	

MECHANICAL					
w	Weight, max	g	176		
D_s	Surface creepage distance	mm (inch)	19.44 (0.765)		
D_a	Air strike distance	mm (inch)	12.10 (0.476)		

PART NUMBERING GUIDE							NOTES								
FDT	32	400	24	7	2	3									
1	2	3	4	5	6	7									

1. FDT — Fast Inverter Disc Thyristor
 2. Design version
 3. Mean on-state current, A
 4. Voltage code
 5. Critical rate of rise of off-state voltage
 6. Group of turn-off time ($\text{dv}_D/\text{dt}=50 \text{ V}/\mu\text{s}$)
 7. Group of turn-on time

Symbol of Group	4	5	6	7	8	8,5	9
$(\text{dv}/\text{dt})_{\text{crit}}, \text{V}/\mu\text{s}$	200	320	500	1000	1600	2000	2500

2) Turn-on time

Symbol of group	4	3	3	2
$t_{gt}, \mu\text{s}$	2.00	2.50	3.20	4.00

3) Turn-off time ($\text{dv}_D/\text{dt}=50 \text{ V}/\mu\text{s}$)

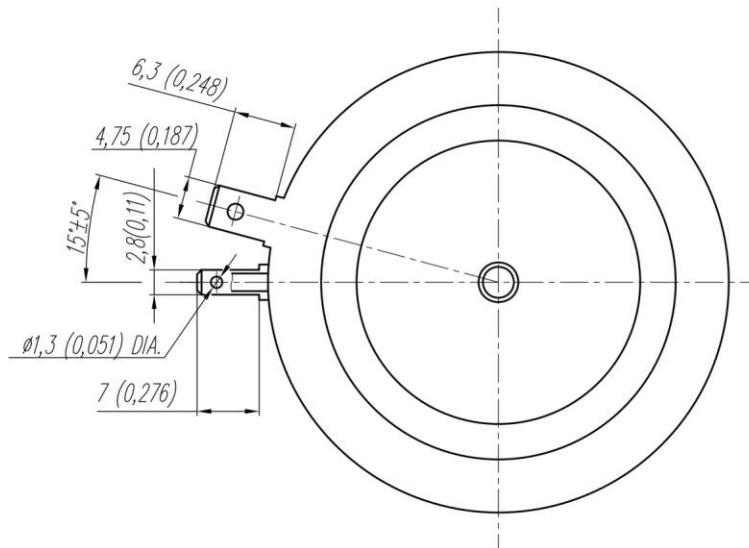
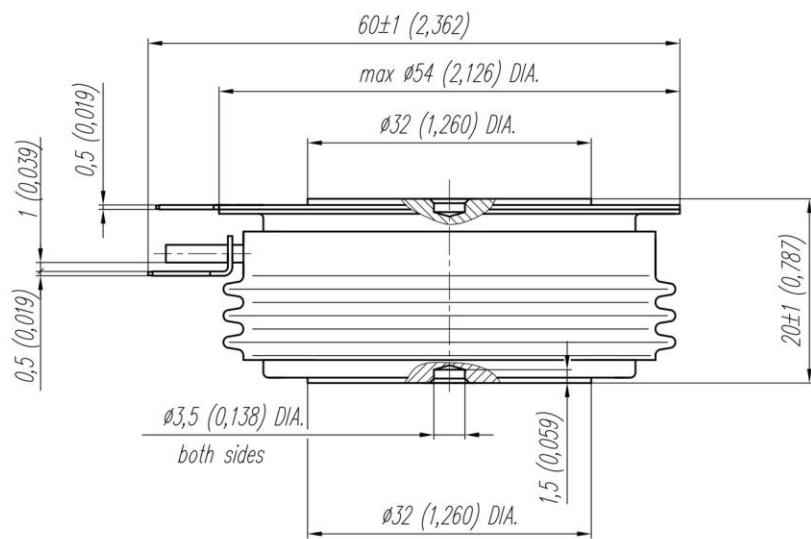
Symbol of group	2	1
$t_{gt}, \mu\text{s}$	50.0	63.0

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OVERALL DIMENSIONS

Package type: T.B3



All dimensions in millimeters (inches)